

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

10. (currently amended) A high voltage semiconductor device comprising:  
a semiconductor substrate, the semiconductor substrate including a plurality of device structures thereon; and  
an interconnect on the semiconductor substrate, the interconnect comprising at least one slot provided in the semiconductor substrate and a plurality of metals at least one metal within the at least one slot, wherein the plurality of metals comprises three metals, wherein the first and second metals fill the slot and the third metal provides an interconnect layer, the at least one metal being of sufficient thickness to carry a high current, wherein the at least one slot is oxidized everywhere except at the bottom of the slot where the interconnect forms a ground strap.

✓ Please cancel claims 11 and 12.

✓ 11. (cancelled)

✓ 12. (cancelled)

13. (currently amended) The semiconductor device of claim ~~12~~ 10 wherein the plurality of metals comprises three metals, wherein the first and second metals fill the slot and the third metal provides an interconnect layer.

14. (original) The semiconductor device of claim 13 wherein the ground strap comprises an ideal short to ground.

15. (original) The semiconductor device of claim 14 wherein the ground strap provides for isolation between components.

16. (currently amended) A high voltage interconnect on a semiconductor substrate comprising:

at least one slot provided in the semiconductor substrate; and

~~at least one a plurality of metals within the slot, the at least one metal being of sufficient thickness to carry a high current, wherein the plurality of metals comprises three metals, wherein the first and second metals fill the slot and the third metal provides an interconnect layer,~~  
wherein the at least one slot is oxidized everywhere except at the bottom of the slot, and the interconnect forms a very low resistance ground strap.

✓ Please cancel claims 17-19.

✓ 17. (cancelled)

18. (cancelled)

19. (cancelled)

20. (original) The interconnect of claim 16 wherein the ground strap comprises an ideal short to ground.

21. (original) The interconnect of claim 16 wherein the ground strap provides for isolation between components.